

ABSTRACT

WIRING MATERIAL AND WIRING BOARD USING THE SAME

A wiring material for TFT-LCD which comprises an Ag alloy containing Ag and Zr as essential components and further one or more metals selected from the group consisting of Au, Ni, Co and Al; and a wiring material which comprises a Cu alloy comprising Au and/or Co and Cu, wherein the alloy has a Cu content of 80 to 99.5 wt % and the sum of a Au content and a Co content of 0.5 to 20 wt %. A film formed using a wiring material comprising the above alloy comprising Ag (or Cu) on a glass substrate or a silicon wafer by the sputtering method has exhibited satisfactorily low electric resistance and also satisfactorily high adhesion strength to the substrate or the wafer.